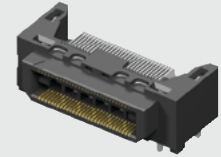


BTH-090-01-F-D-A



BTH SERIES

(0.50 mm) .0197"

BASIC BLADE & BEAM HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTH

Insulator Material: Black LCP

Contact Material: Phosphor Bronze

Plating: Au or Sn over 50 μm (1.27 μm) Ni

Current Rating: 2.0 A per pin (2 pins powered)

Flammability Rating: UL 94 VO

Operating Temp Range: -55 °C to +125 °C

Voltage Rating: 175 VAC

Max Cycles: 100

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes

SMT Lead Coplanarity: Vertical= (0.10 mm) .004" max (030-090)

Vertical= (0.15 mm) .006" max (120-150)*

Right-angle= (0.15 mm) .006" max (030-090)*

*(.004" stencil solution may be available; contact IPG@samtec.com)

Board Stacking: For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

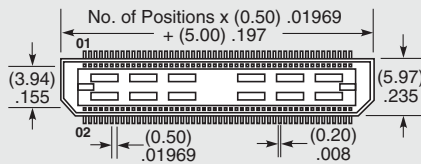
- 30 μm (0.76 μm) Gold
- Edge Mount Capability
- 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

Note: Some lengths, styles and options are non-standard, non-returnable.



Mates with: BSH

-030, -050, -060, -090, -120, -150



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197

*Processing conditions will affect mated height.

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

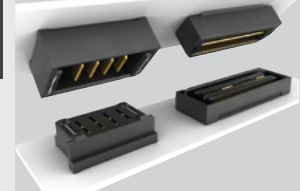
-C*
= Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

*Note: -C Plating passes 10 year MFG testing

-K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (120 positions maximum)

POWER/SIGNAL APPLICATION

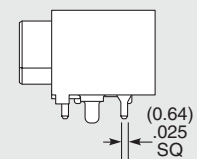
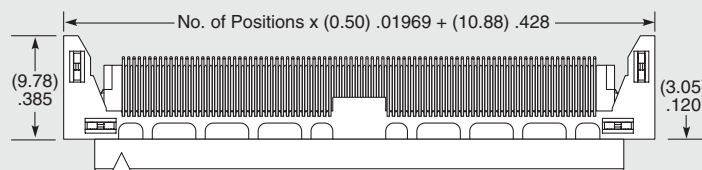


Compatible with UMPT/UMPS for flexible two-piece power/signal solutions



Mates with: BSH

-030, -060, -090



-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

-K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.